

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

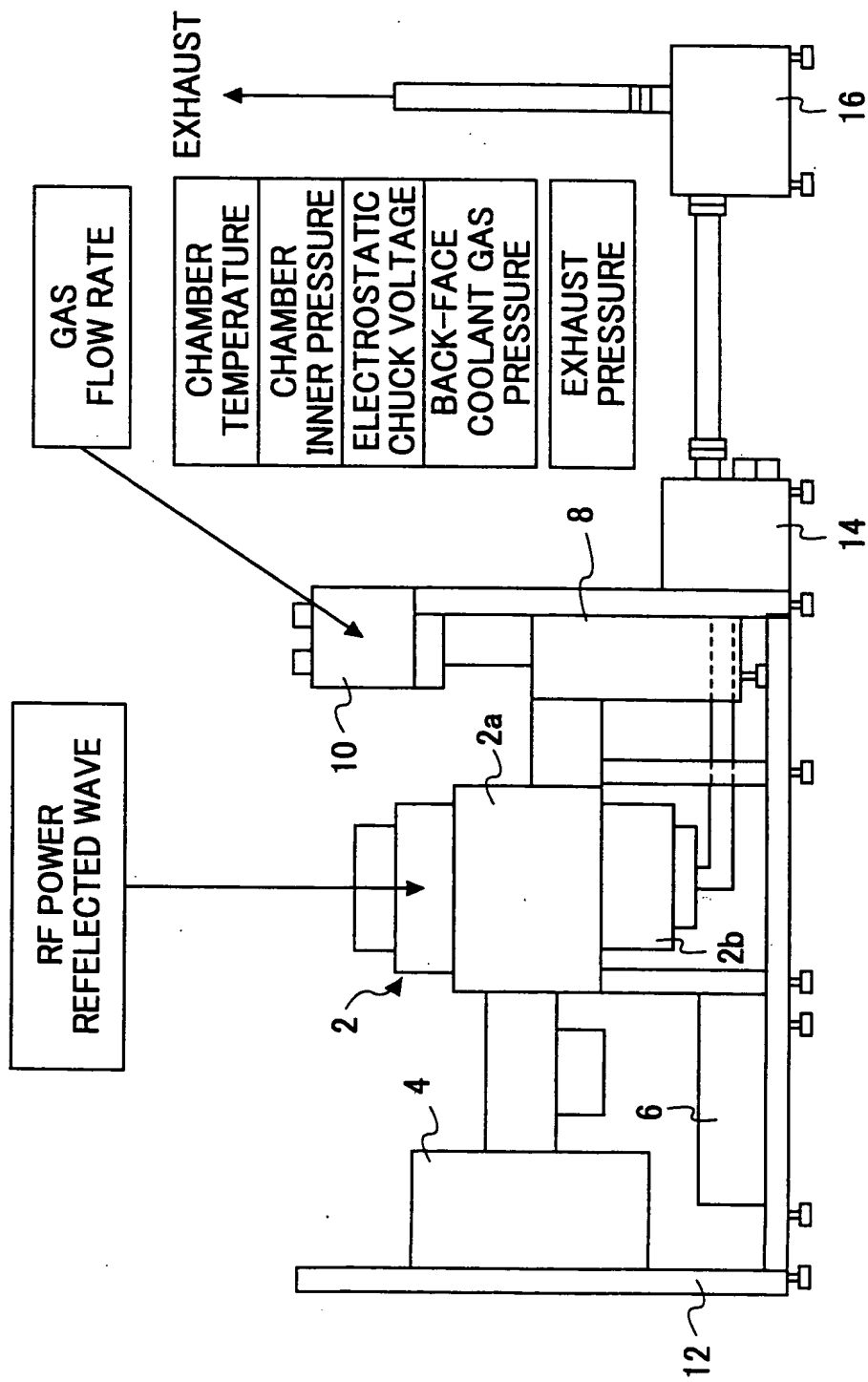
Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

FIG.1



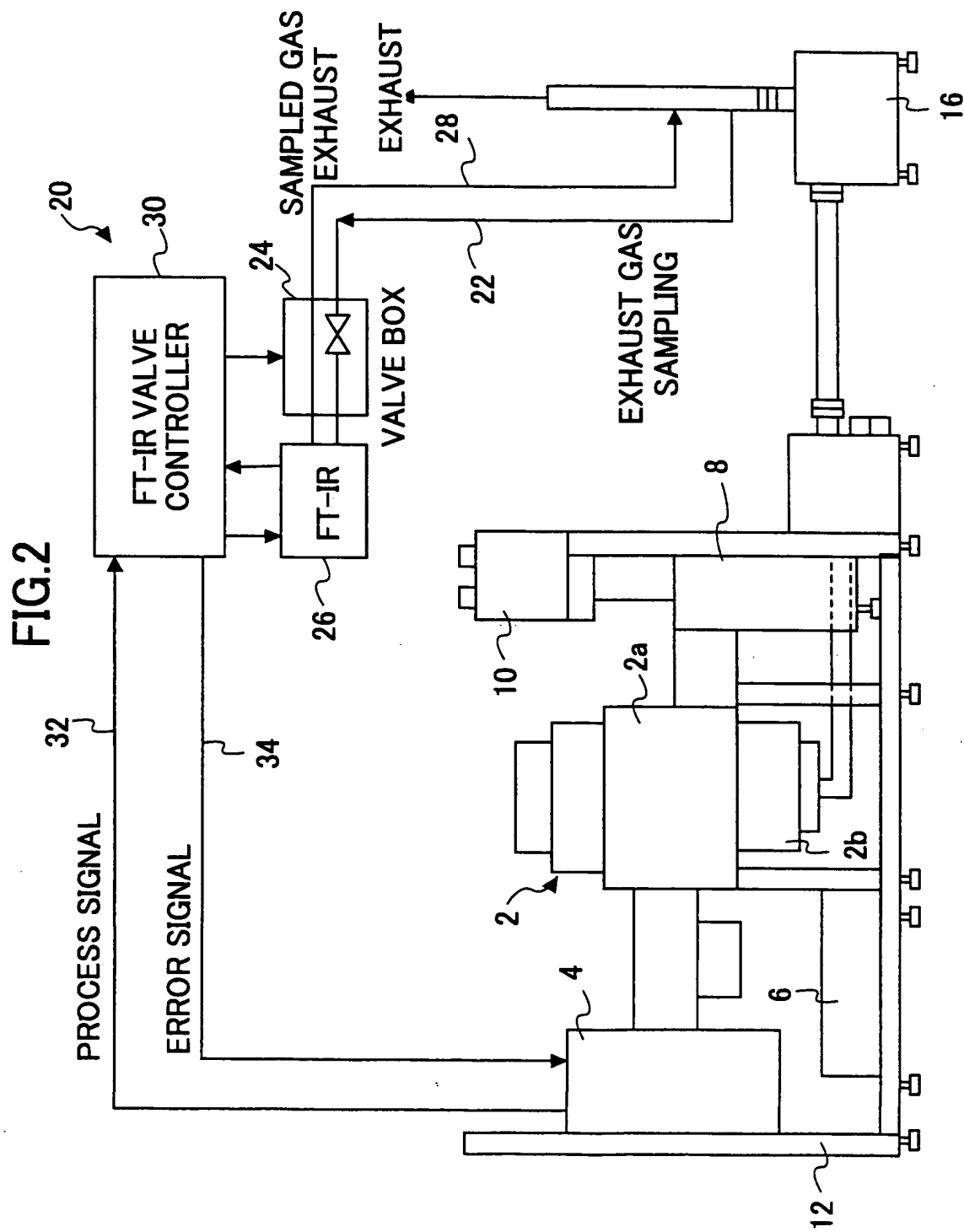
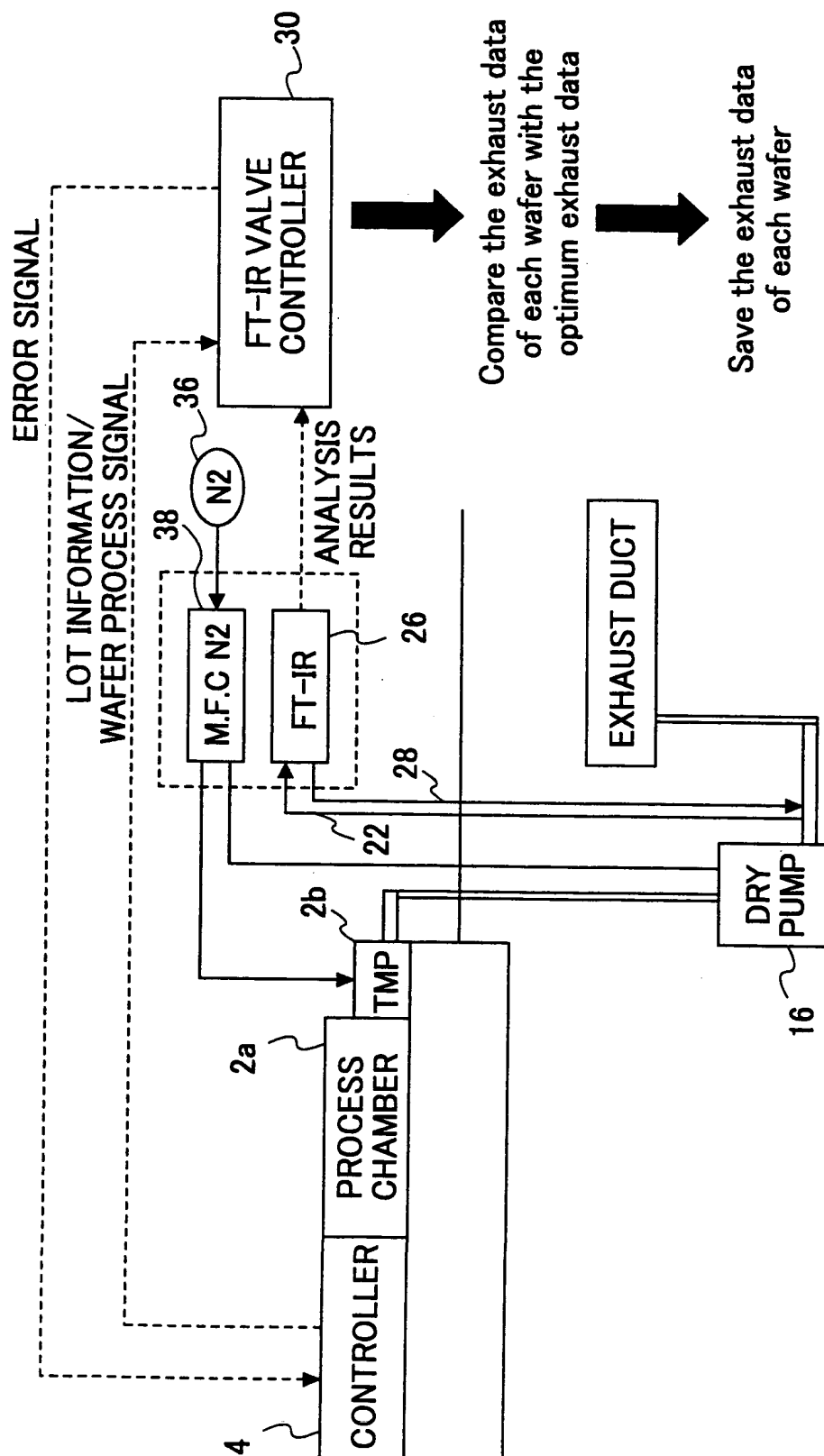


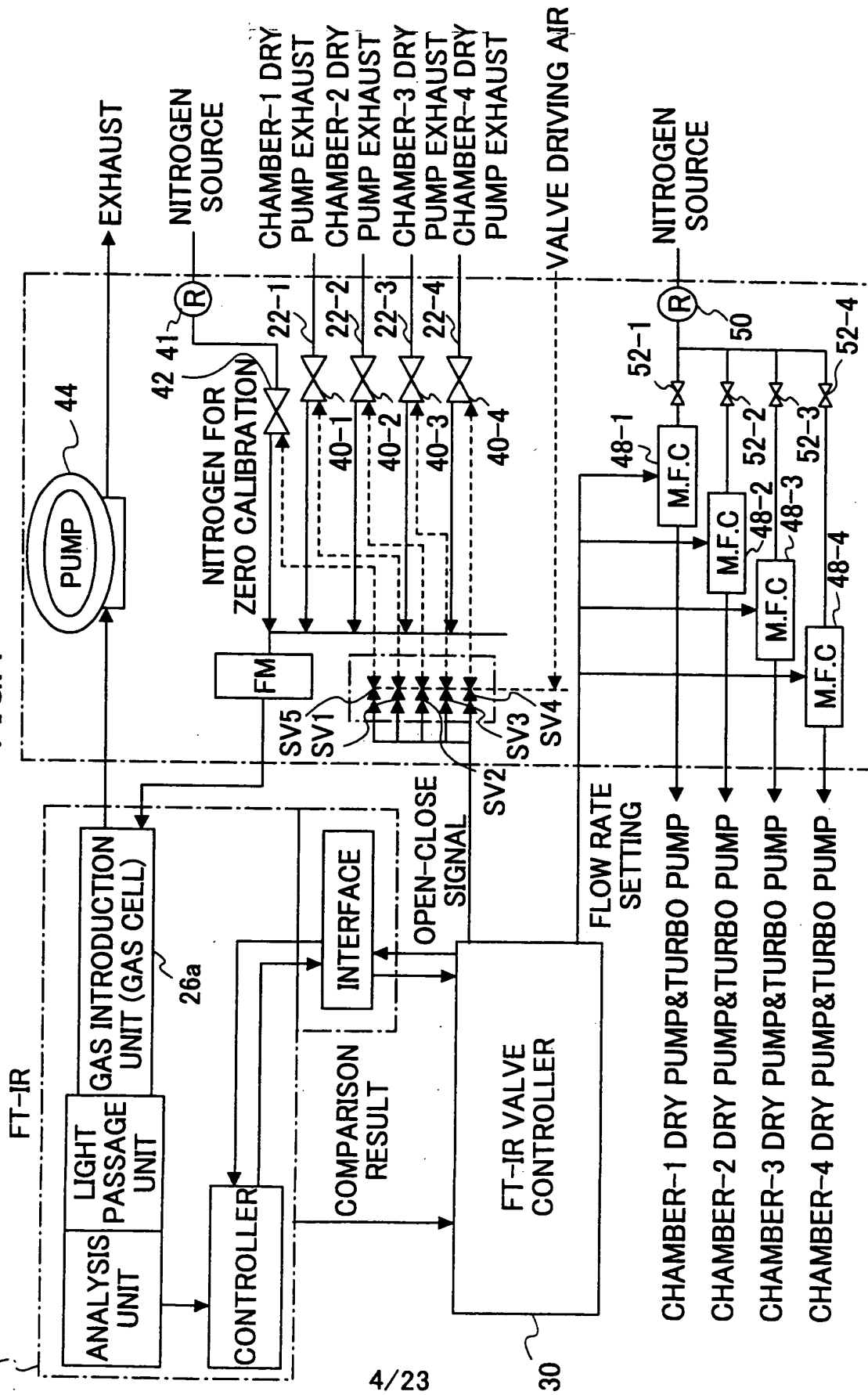
FIG.3

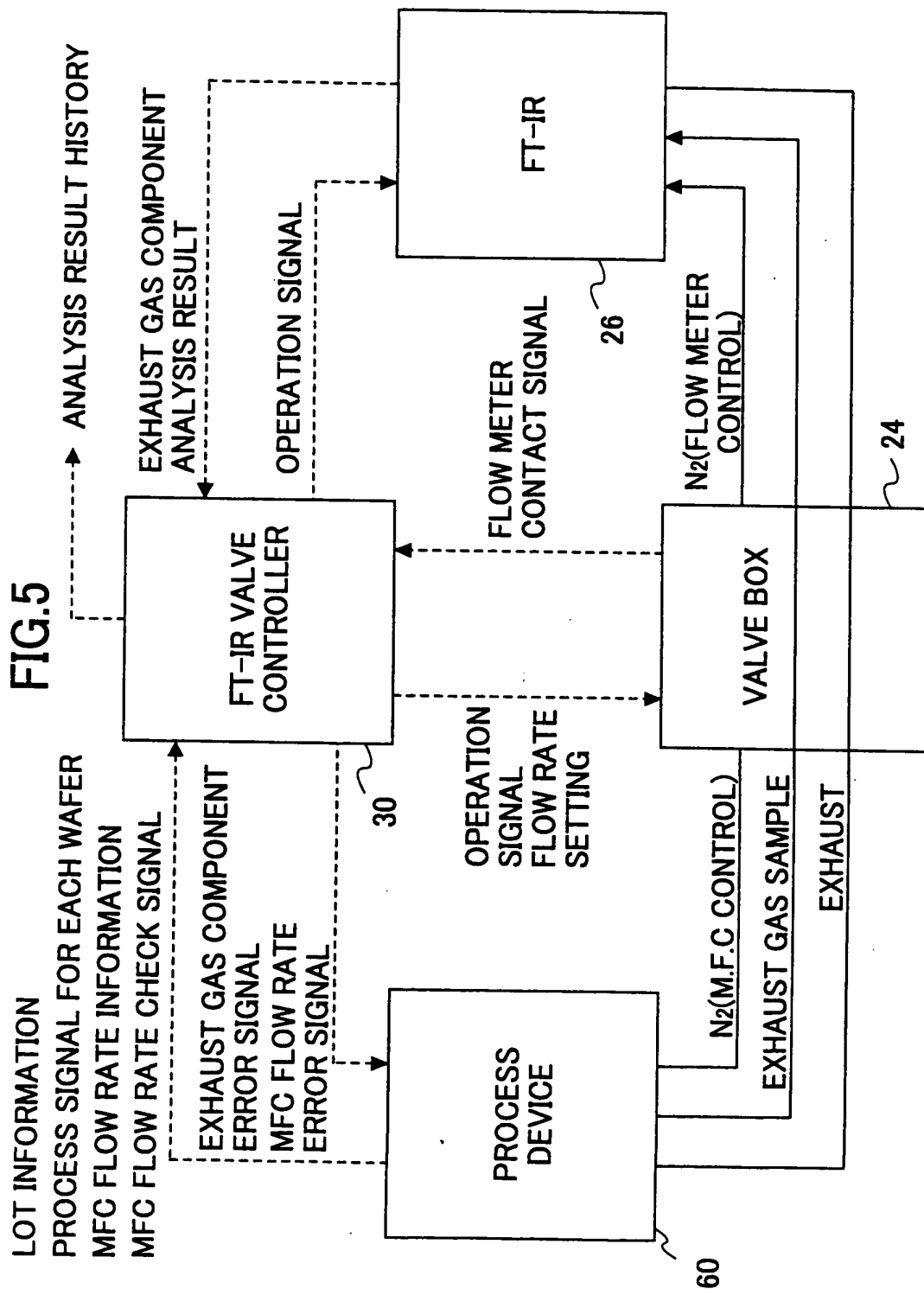


Compare the exhaust data
of each wafer with the
optimum exhaust data

Save the exhaust data
of each wafer

FIG. 4





FT-IR controller

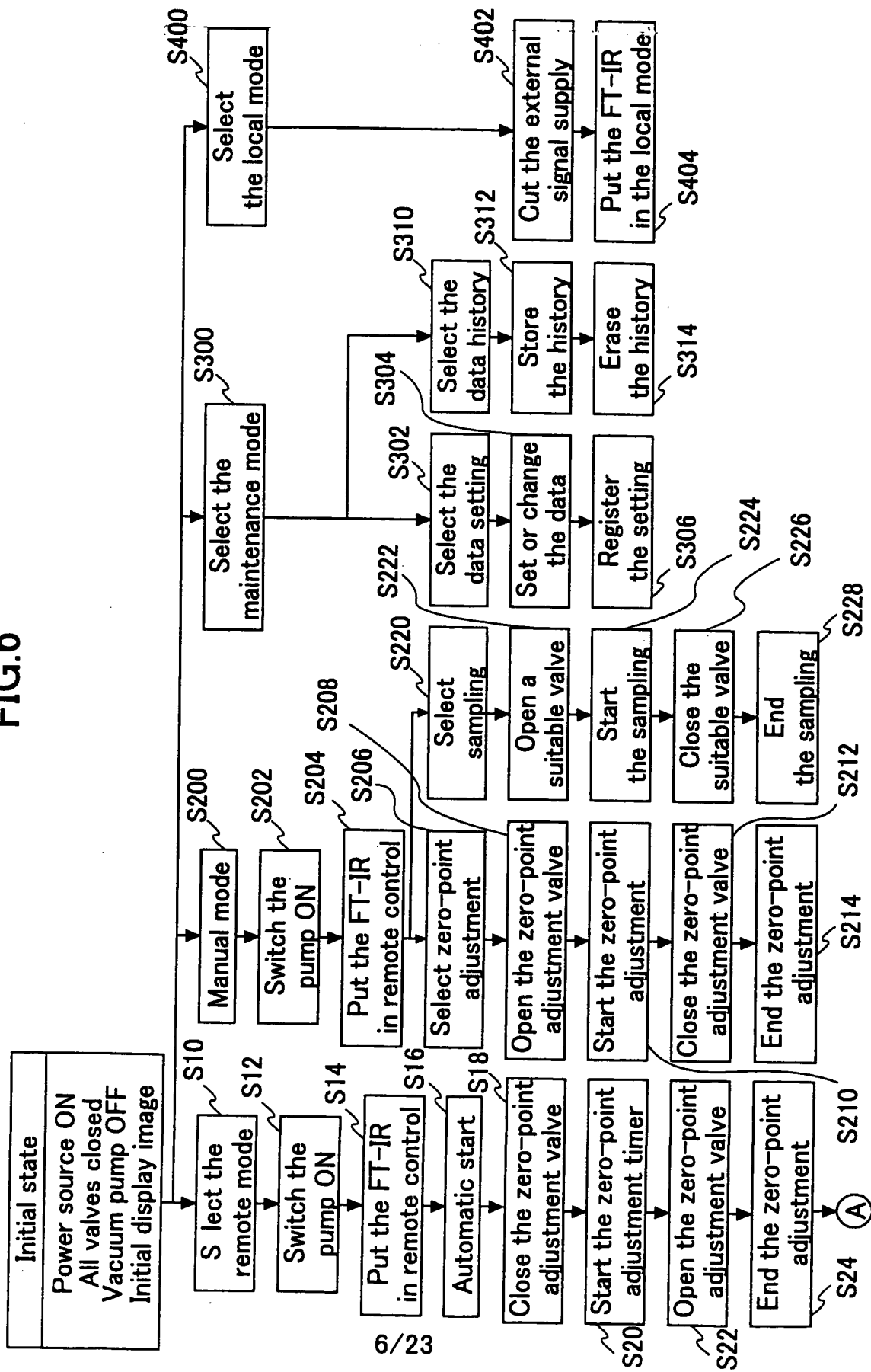


FIG. 7

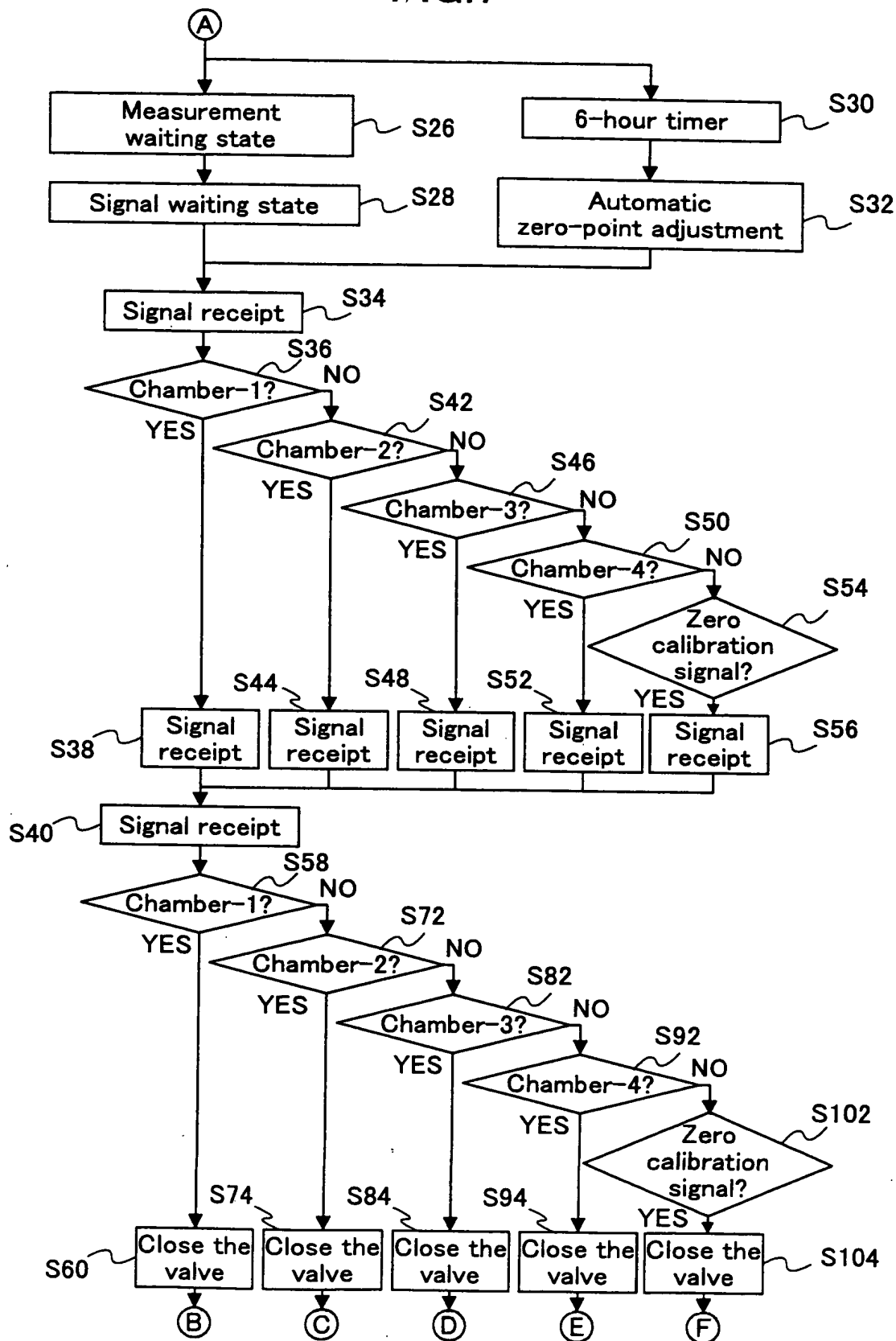


FIG.8

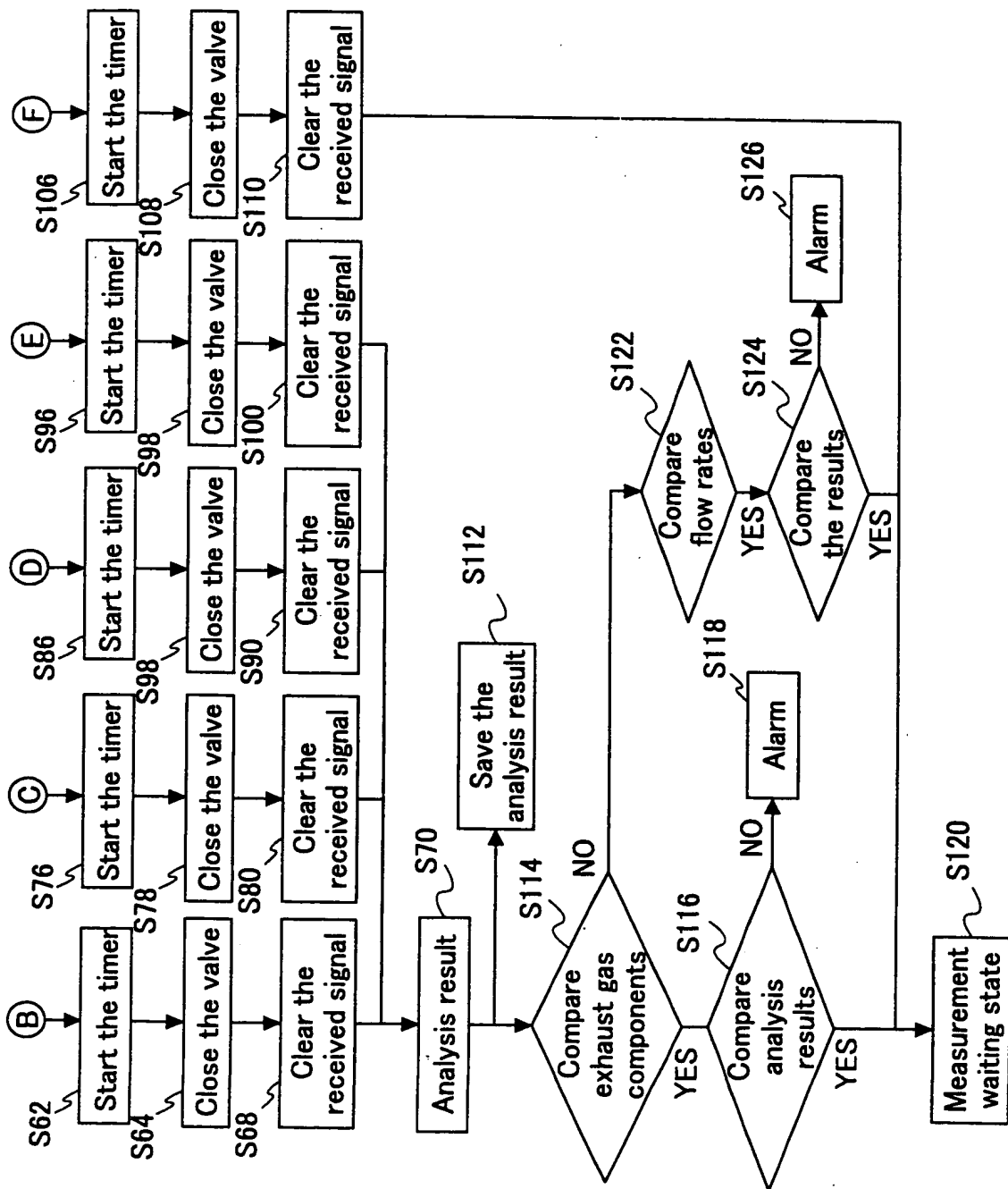


FIG.9

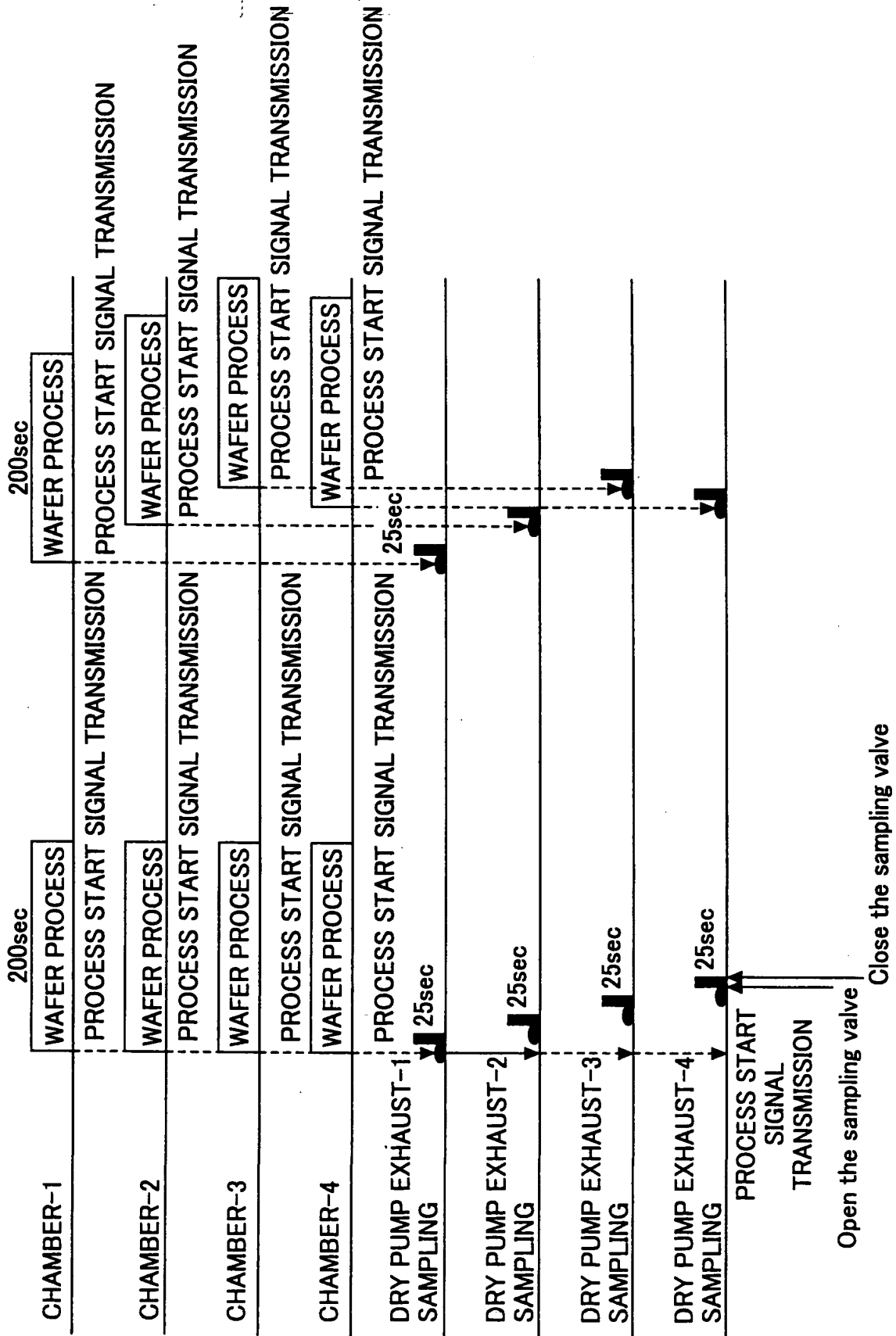


FIG.10

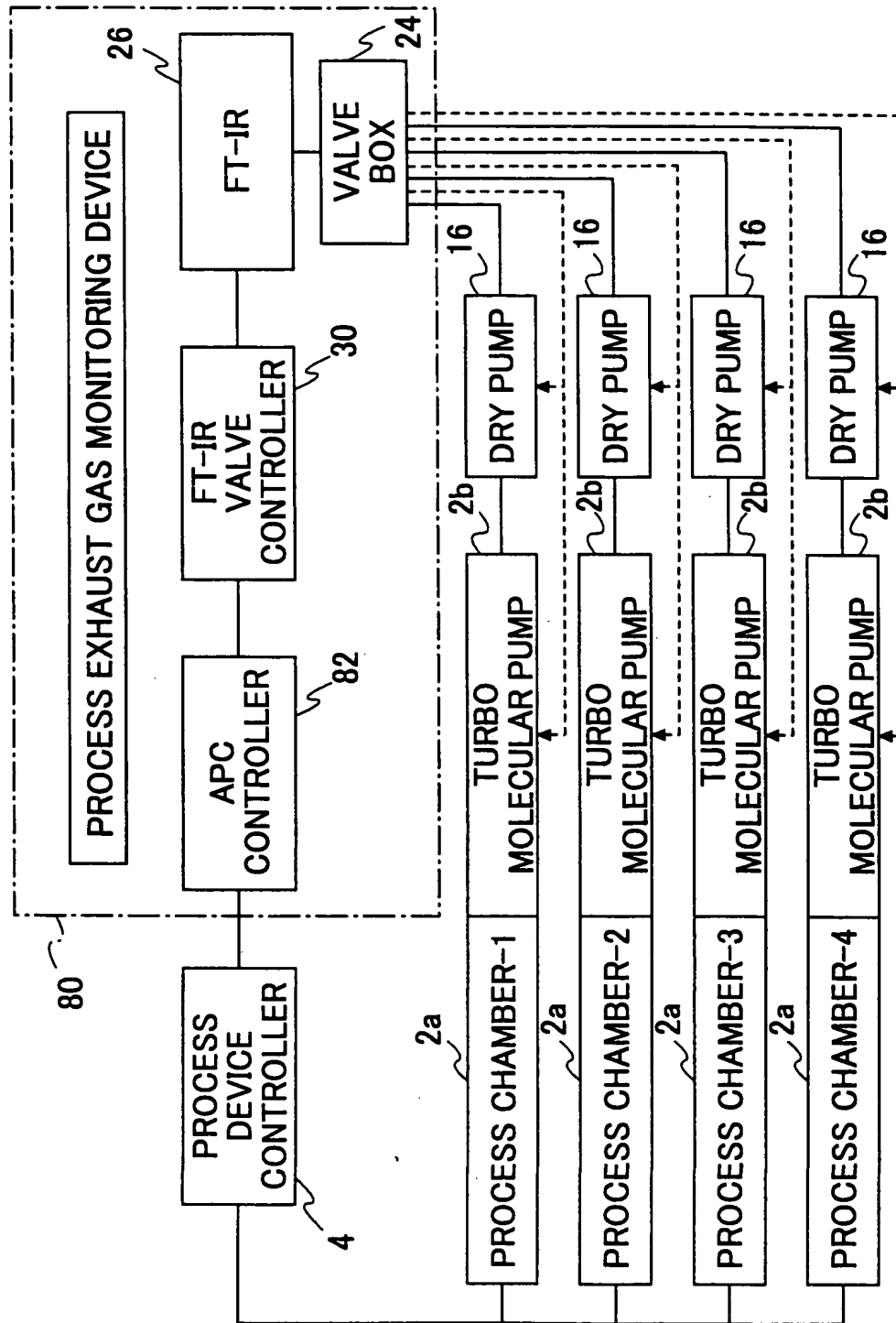
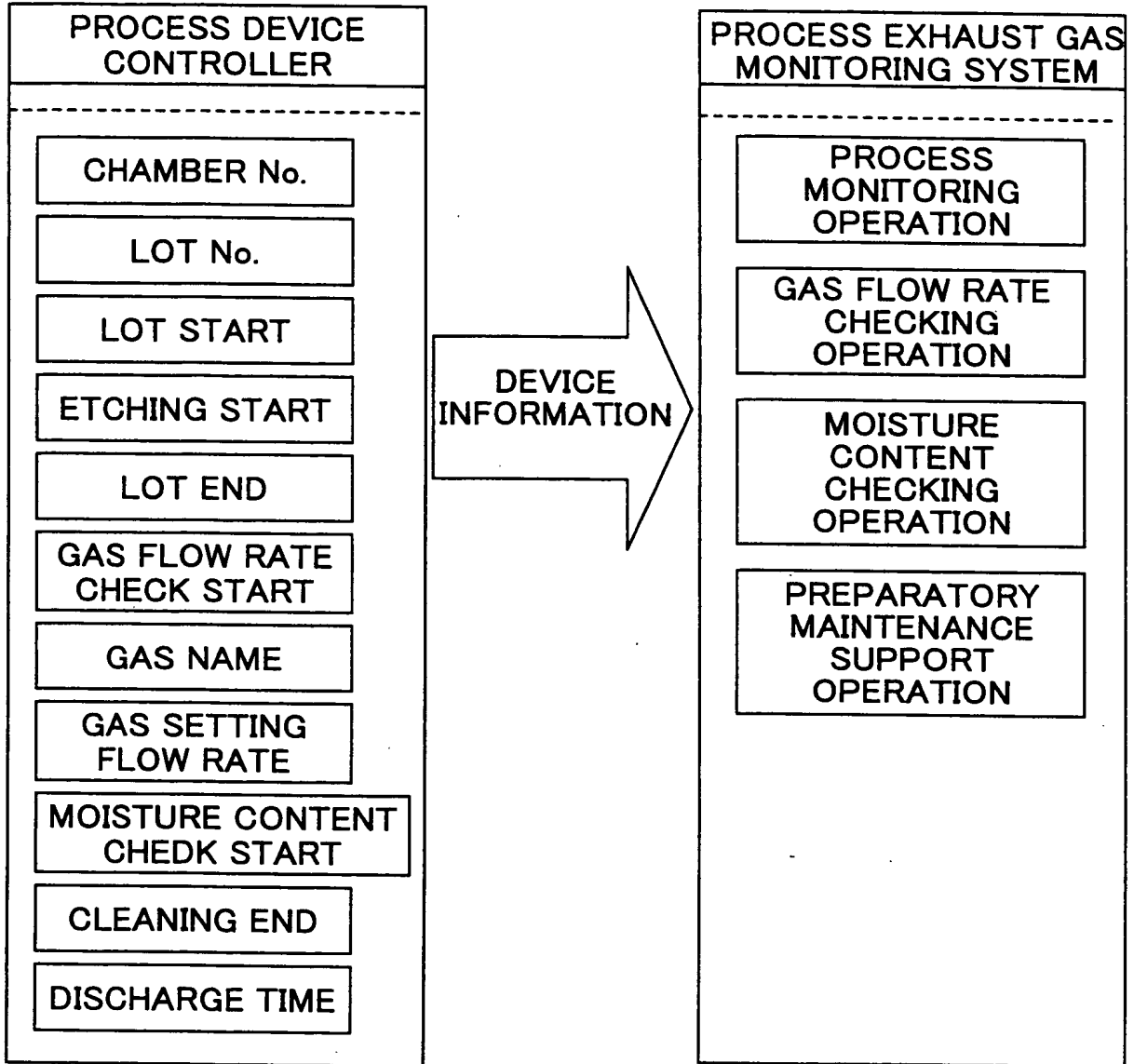
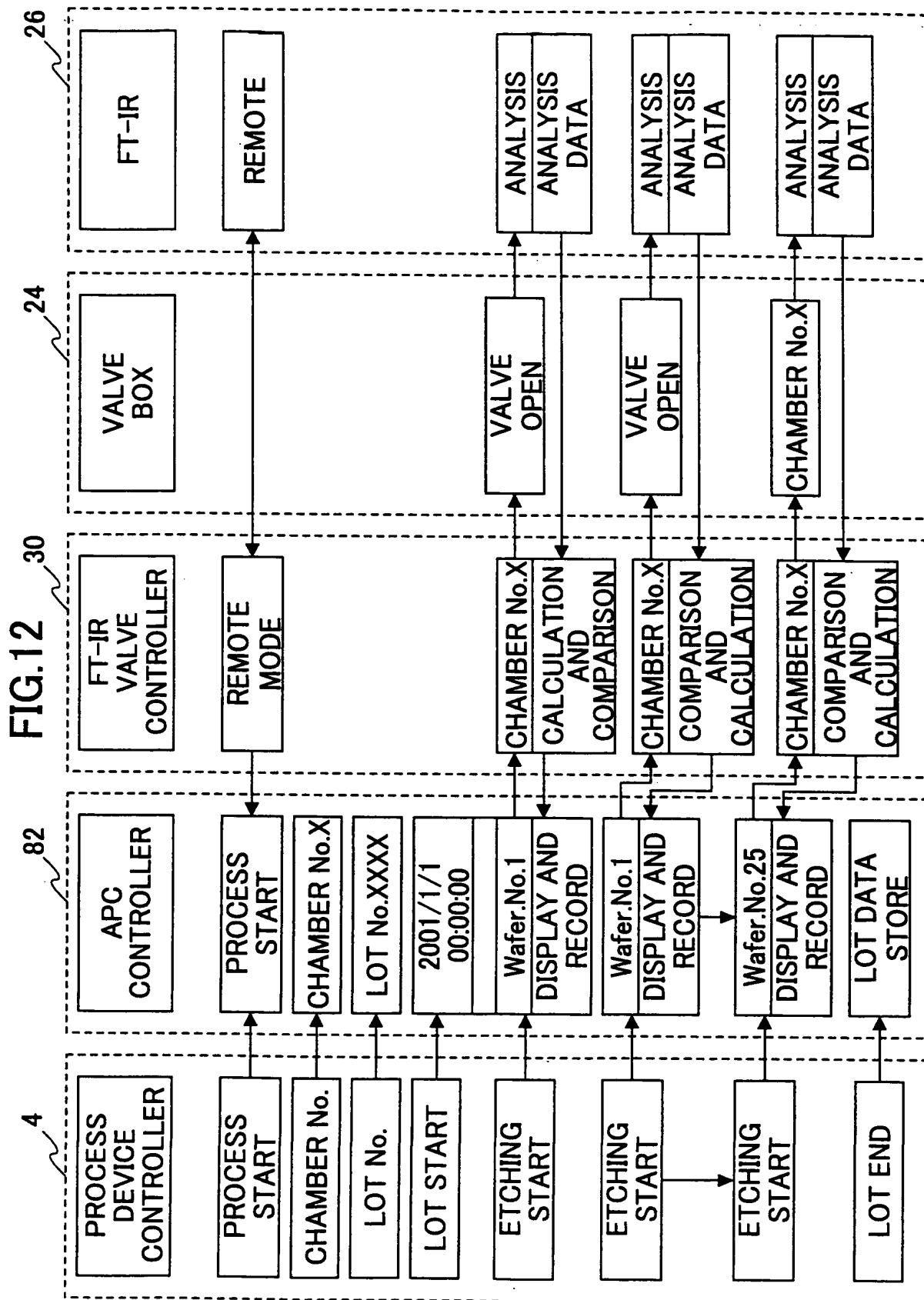


FIG.11





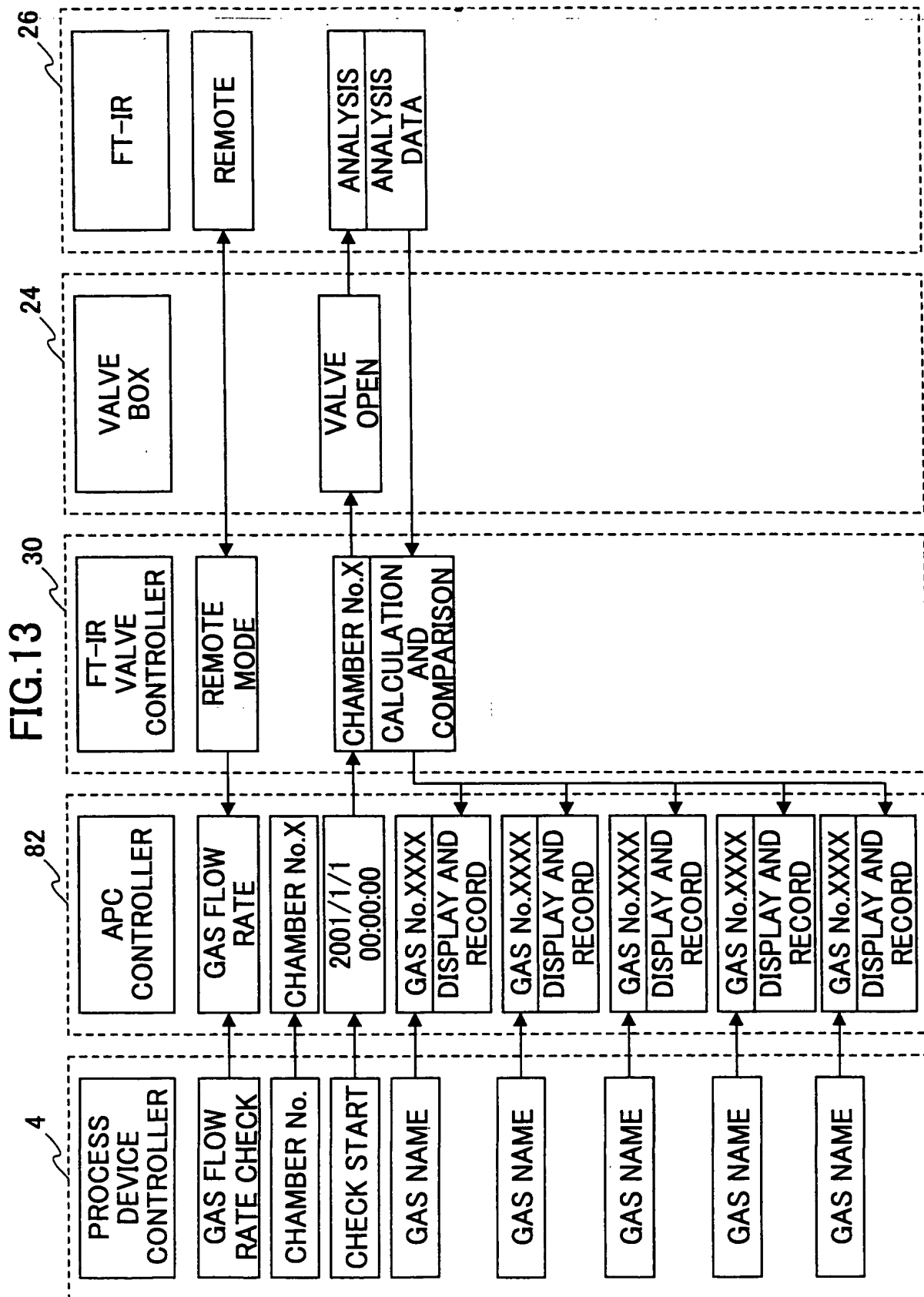


FIG.14

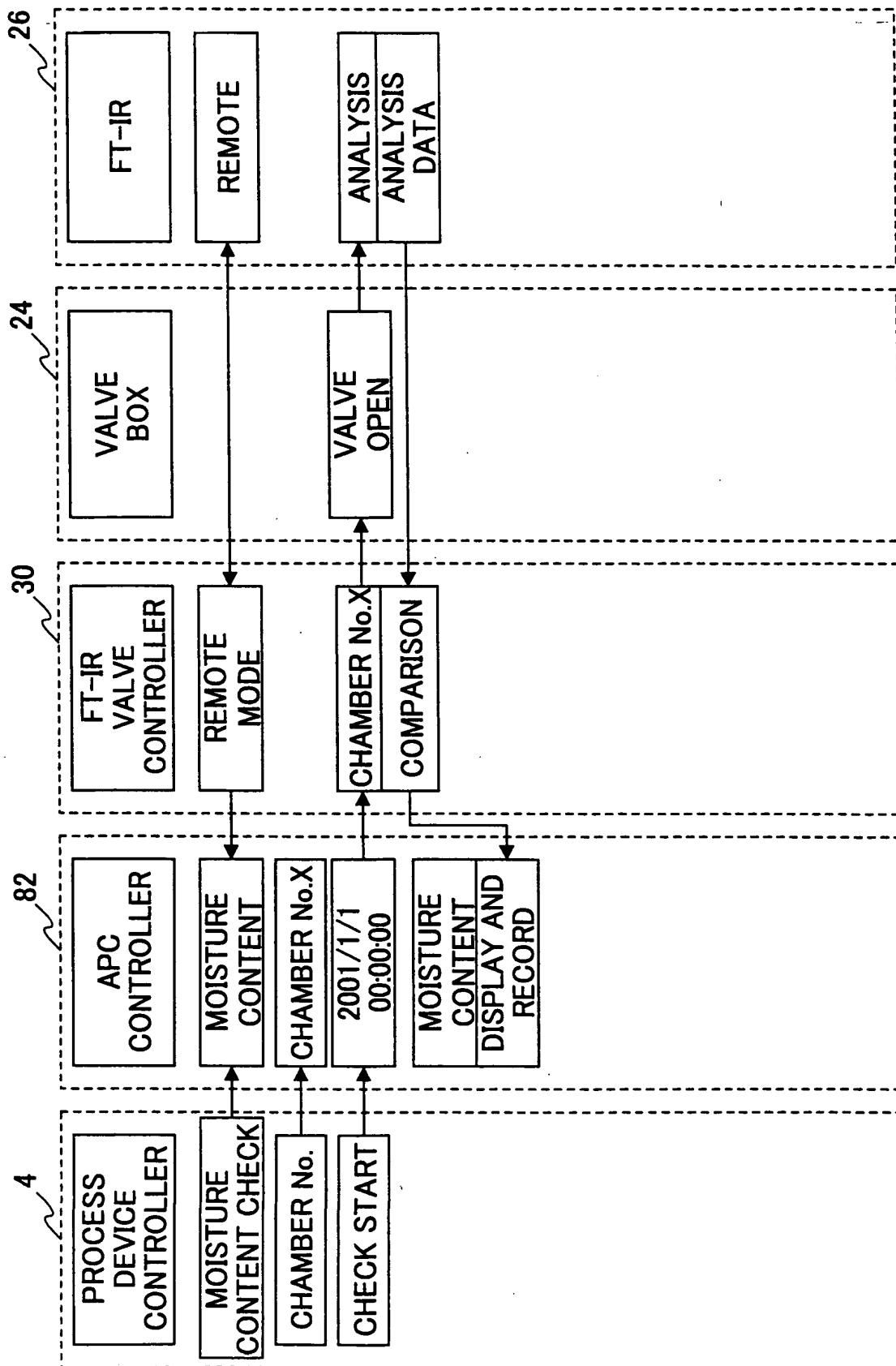


FIG.15

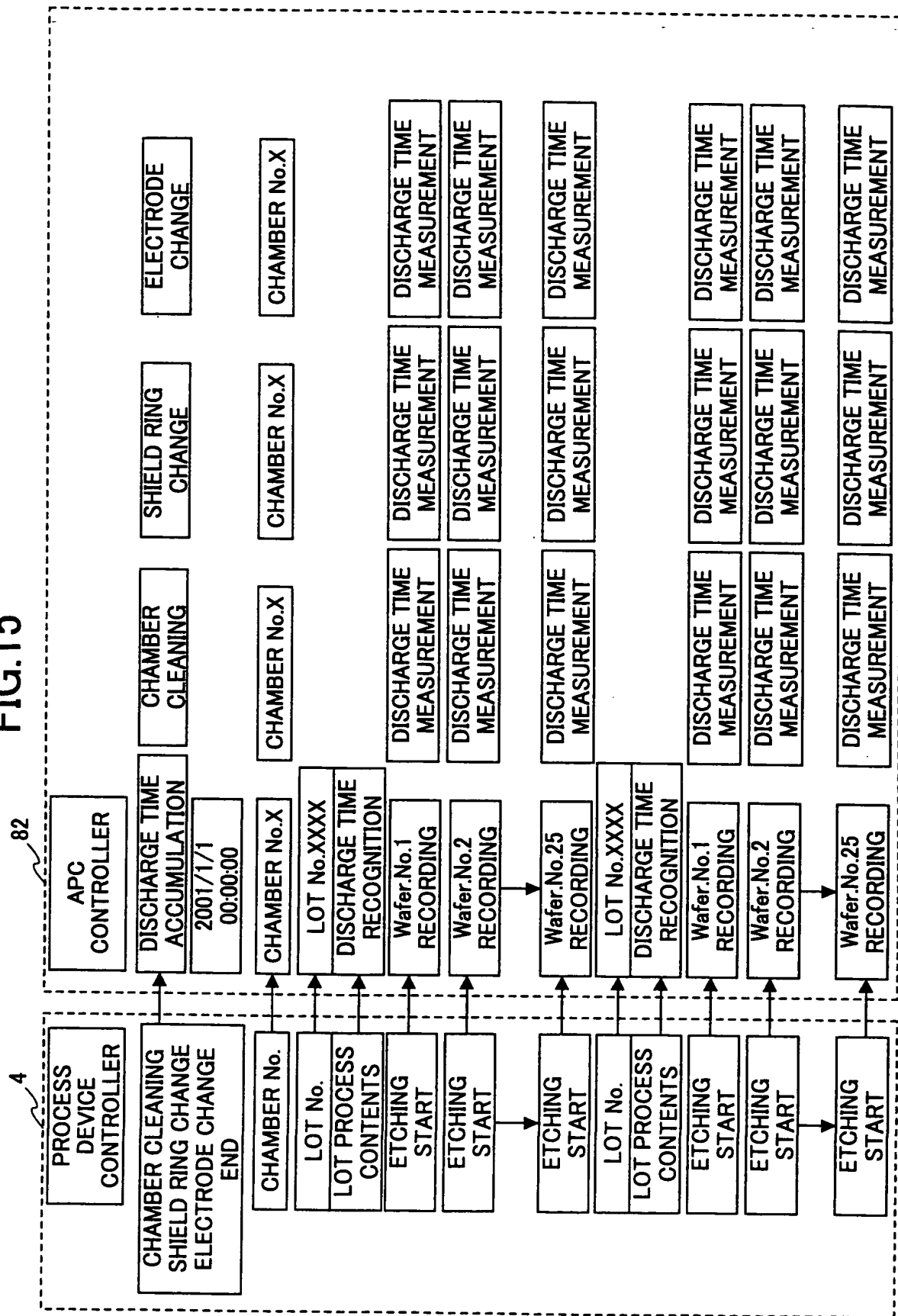


FIG.16

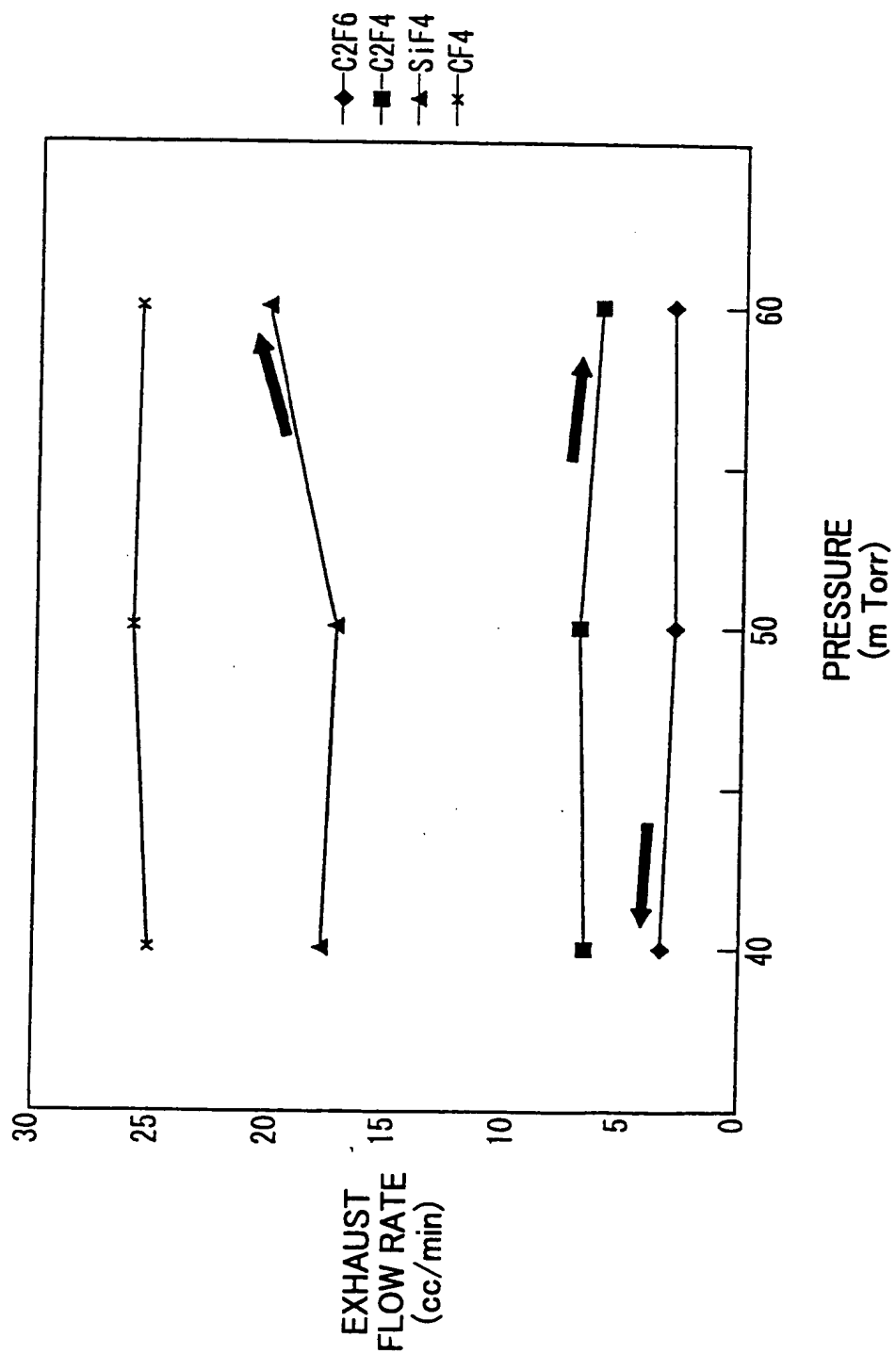


FIG.17

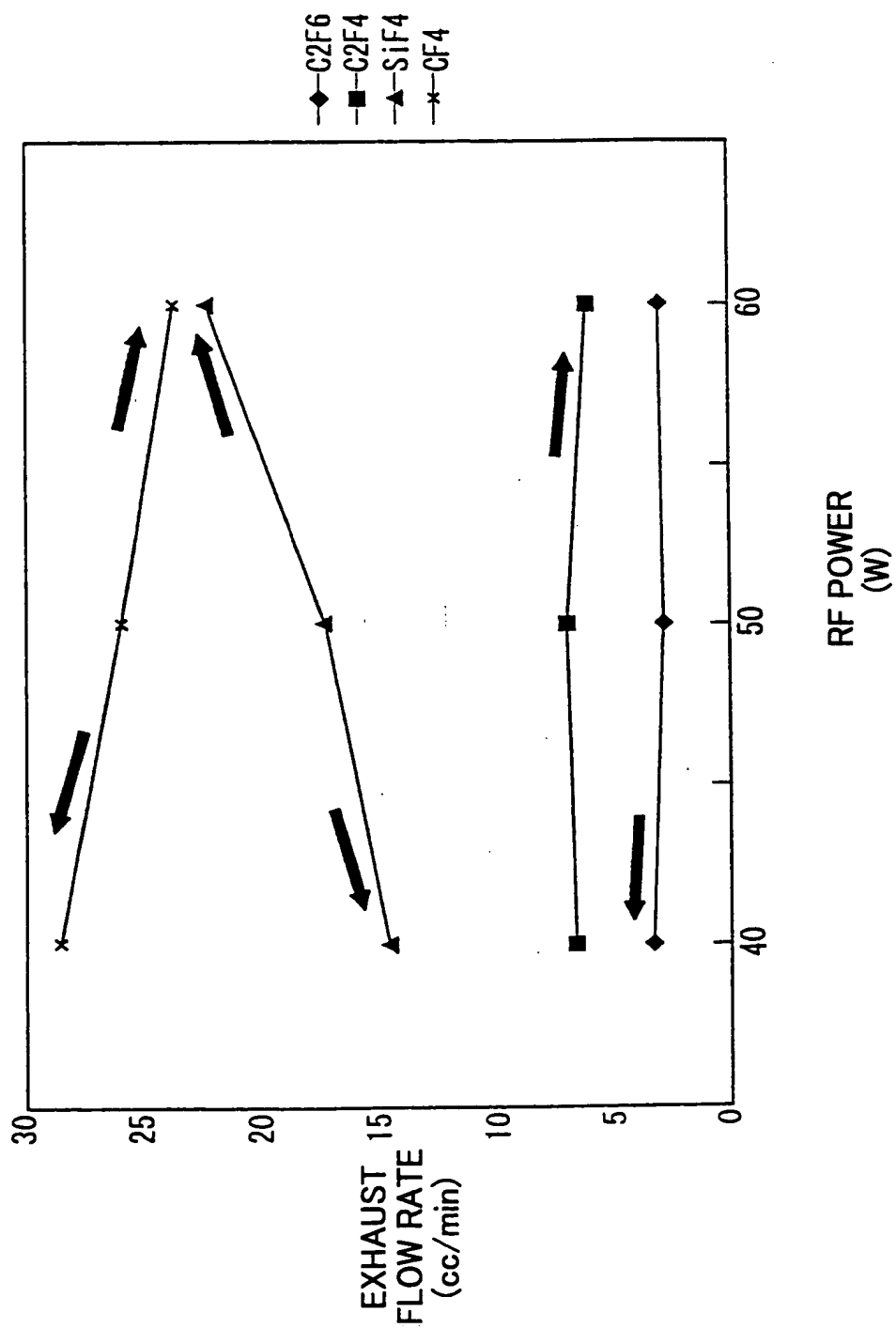


FIG.18

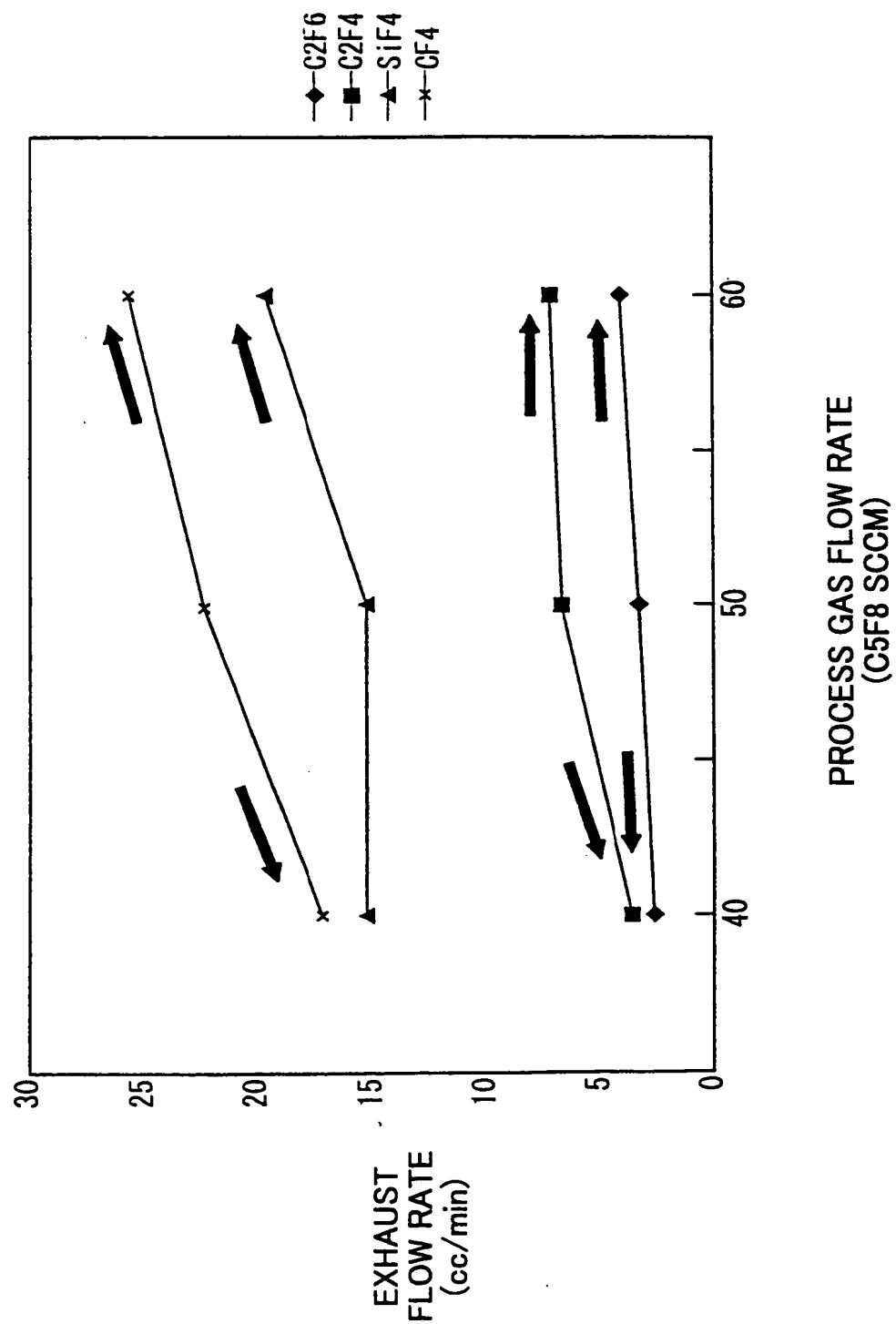


FIG.19A CF₄

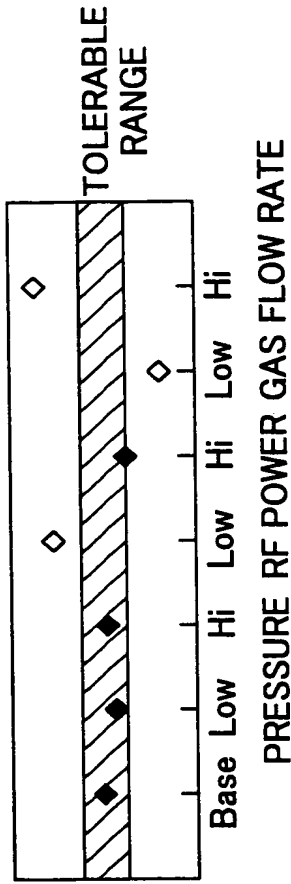


FIG.19B SiF₄

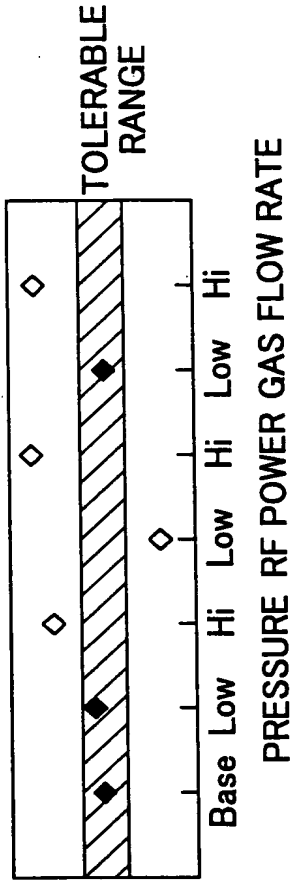


FIG.19C C₂F₄

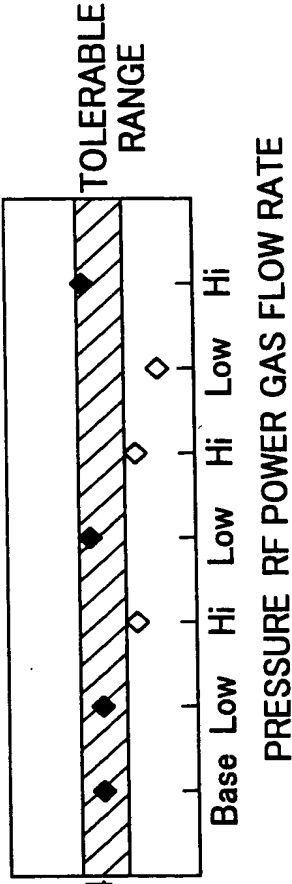


FIG.19D C₂F₆

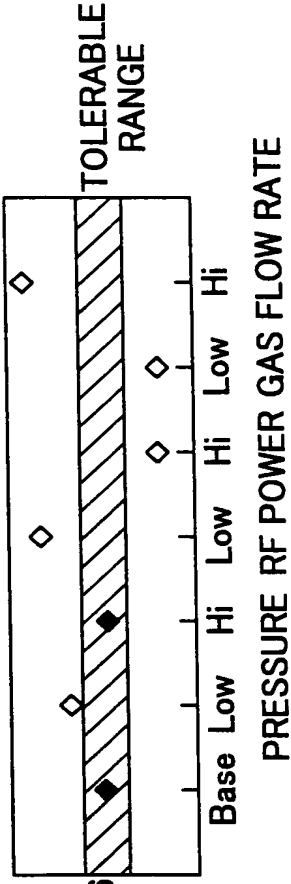


FIG.20

GAS TYPE PARAMETER		CF4	SiF4	C2F4	C2F6	RECOGNITION SIGNAL
CHAMBER INNER PRESSURE	Low	◆	◆	◆	◇	0001
		0	0	0	1	
	Hi	◆	◇	◇	◆	0110
		0	1	1	0	
RF POWER	Low	◇	◇	◆	◇	1101
		1	1	0	1	
	Hi	◆	◇	◇	◇	0111
		0	1	1	1	
GAS FLOW RATE (C5F8)	Low	◇	◆	◇	◇	1011
		1	0	1	1	
	Hi	◇	◇	◇	◇	1111
		1	1	1	1	

FIG.21

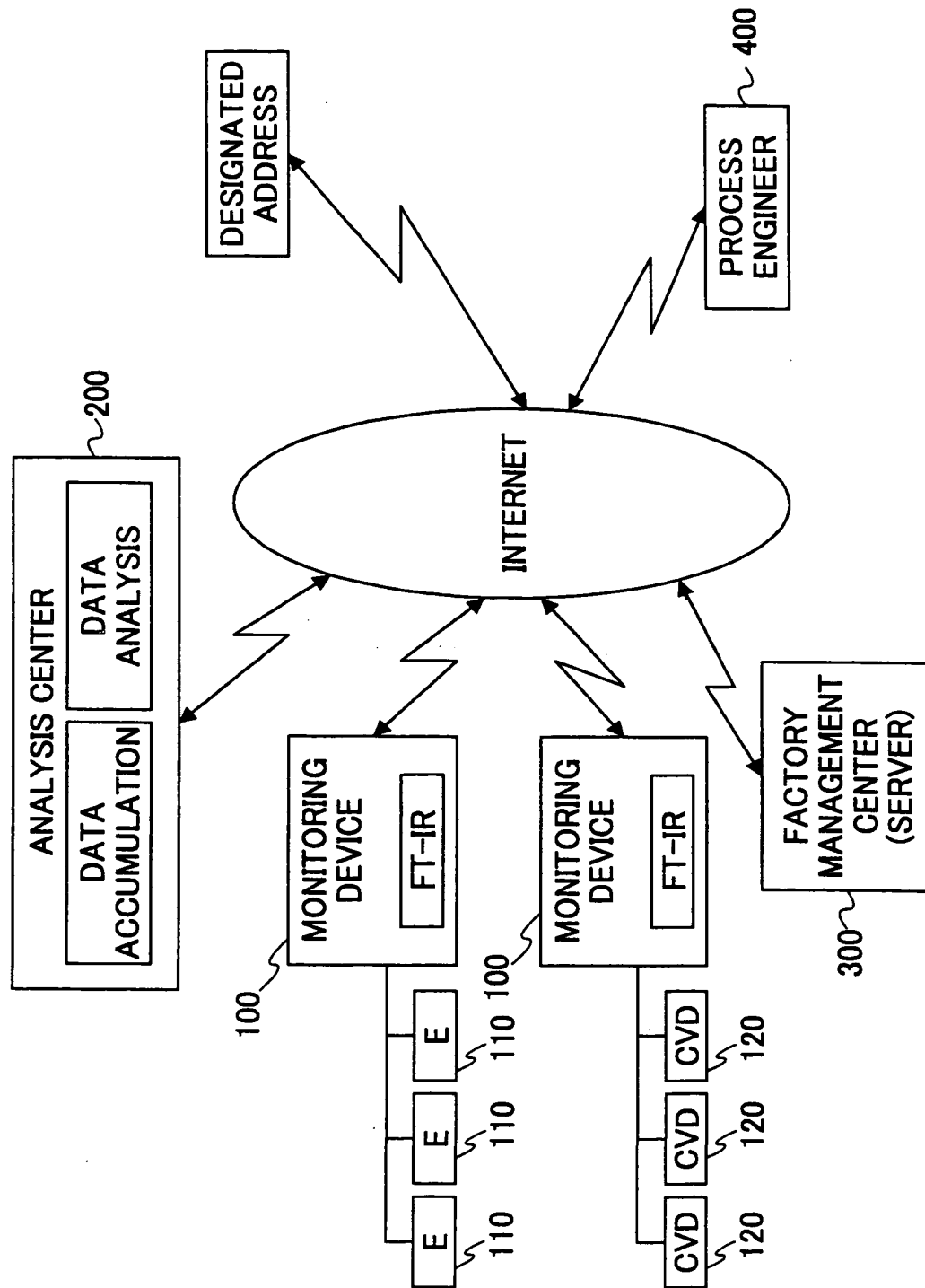


FIG.22

DISPLAY SCREEN

Error in Process Conditions	Cause of Failure
The chamber inner pressure may have decreased.	Shield ring damage
<u>Please check the chamber inner pressure for a decrease.</u>

FIG. 1 is a schematic diagram of a plasma processing system. The system includes a Process Chamber (510) containing a W. Wafer and a Susceptor. A Gas Supply Mechanism (512) is connected to the chamber. A Turbo Pump (530) and a Dry Pump (540) are connected to the chamber. A Cleaner Device (570) is connected to the Dry Pump. A Control Unit (610) is connected to the Turbo Pump, Dry Pump, and Cleaner Device. A Valve Switch Unit (620) is connected to the Control Unit. A Work Space (580) is connected to the Chamber. A Matching Box (514) and RF Power Source (516) are connected to the Chamber. A Gas Source (520) is connected to the Chamber. A Process Gas inlet is shown at the top. Various sensors (X1, X2, X3, X4, X5, X6, X7, X8) are located throughout the system.